

ABSTRACT

A semiconductor substrate integrated with interconnections and circuit components. A silicon backplane is processed with silicon processing to provide electrical connectivity for circuit elements. In one embodiment functional circuit elements, e.g., MEMS, switches, filters, are integrated on the silicon backplane. In one embodiment the function circuit elements are monolithically processed into the silicon backplane. In one embodiment the silicon backplane includes interconnections for integrated circuits on different substrates to be bonded to the silicon backplane.